

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
29 December 2005 (29.12.2005)

PCT

(10) International Publication Number
WO 2005/123628 A1

(51) International Patent Classification⁷: **C04B 37/00**,
37/04, C03C 27/08, 27/00, B32B 18/00, 31/14, H01L
41/24, 23/15, B81C 3/00

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(21) International Application Number:
PCT/SG2005/000186

(22) International Filing Date: 8 June 2005 (08.06.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/868,714 15 June 2004 (15.06.2004) US

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FOR SCIENCE, TECHNOLOGY & RESEARCH**
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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA,
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SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC,
VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,
FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO,
SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, ML, MR, NE, SN, TD, TG).

Declaration under Rule 4.17:

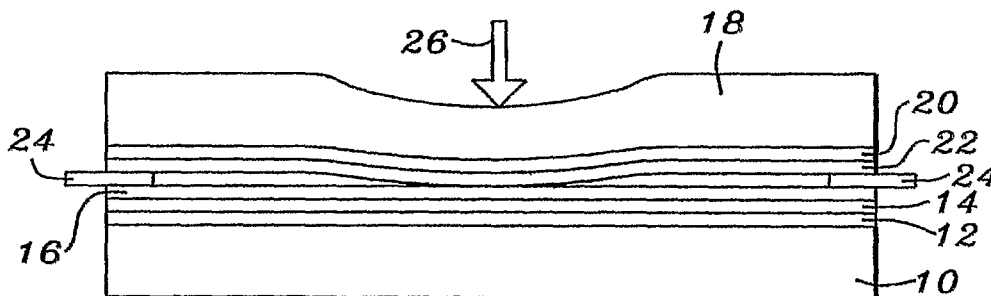
— of inventorship (Rule 4.17(iv)) for US only

Published:

— with international search report

[Continued on next page]

(54) Title: ANODIC BONDING PROCESS FOR CERAMICS



(57) Abstract: A method of bonding a first ceramic component and a second ceramic component is provided. A first conductive layer is formed over the upper surface of the first ceramic component. An intermediate film is formed over the first conductive layer. A second conductive layer is formed over the lower surface of the second ceramic component. The second ceramic component is stacked over the first ceramic component wherein the second conductive layer on the second ceramic component opposes the intermediate film on the first component. The first and second ceramic components are anodically bonded. When the second ceramic component is a silicon or semiconductor layer, the second conductive layer may be omitted.

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